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Die-Attach
ME8630-DA

100% Solid

Low Viscosity
Fine Pitch with Extra-Fine Silver
Long Pot-Life

IDEAL FOR:

- In-line Die-Attach**
- Large and Small Dies**
- Stamping dispensing**
- LED and other smaller dies**

DESCRIPTION:

ME8630-DA is an extra fine silver filled 100% solid low viscosity die-attach for finer pitch application. It is a low stress, low temperature curable die-attach adhesive paste. This single component, silver filled paste is electrically and thermally conductive. It is highly thixotropic with outstanding compatibility for bonding different adherends. The relatively medium Tg and modulus made it suitable for bonding both smaller and relatively large devices.

ME8630-DA has been designed to eliminate bleeding on both silver plated copper and alloy 42 leadframes. It maintains more than 300 psi bond strength at 250°C for high temperature wire-bonding.

AVAILABILITY:

ME8630-DA is available in syringes for automatic needle dispense applications or in jars.

APPLICATION PROCEDURES:

- (1) Thaw to ambient temperature for 30 minutes before opening jar or using syringes.
- (2) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 30 min)	<4x10 ⁻⁴ ohm-cm
Dielectric Strength (Volts/mil)	Not Applicabl
Glass Transition Temp.(°C)	80
Current Carrying Capabilities	>20 Amp/mm ²
Lap-Shear Strength	NA
Device Push-off Strength	>2400 psi >16.6 N/mm ²
Hardness (Type)	80 (D)
Cured Density (gm/cc)	3.5
Thermal Conductivity	>60 Btu-in/hr-ft ² -°F >8.6 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	40
Maximum Continuous Operation Temp. (°C)	150
Avg. Viscosity(5 rpm, 24°C) (Brookfield DV-1,spindle CP51)	8,000 cp

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

<u>Temperature</u>	<u>Time</u>
125°C	60 min.
150°C	30 min.
175°C	5 min

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr

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(3) Cure according to the recommended schedules.

25°C

30 day

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